

| <b>CICMT Program Grid</b>   |   |   |   |
|---|---|---|---|
| <b>Monday, April 24</b>   |   |   |   |
| 4:00 pm – 7:00 pm   | Registration  |   |   |
| 6:00 pm - 7:00 pm   | Opening Reception   |   |   |
| <b>Tuesday, April 25</b>  |   |   |   |
| 7:00 am – 5:30 pm   | Registration  |   |   |
| 10:00 am - 7:00 pm  | Exhibit Hours   |   |   |
| 8:30 am – 9:00 am   | <b>Keynote Presentation</b><br><b>Title:</b> MEMS Technologies for Single-Chip RF Front Ends<br><b>Speaker:</b> Clark Nguyen, University of Michigan  |   |   |
| 9:00 am – 9:30 am   | <b>Keynote Presentation</b><br><b>Title:</b> New Applications in Implantable Medical Devices<br><b>Speaker:</b> Joyce Yamamoto, Medtronic   |   |   |
| 9:30 am – 10:00 am  | <b>Keynote Presentation</b><br><b>Title:</b> A Specialist Manufacturer's Outlook on the Future of Ceramics and Ceramic Microsystems<br><b>Speaker:</b> Franz Bechtold, Via Electronics  |   |   |
| 10:00 am – 10:30 am   | Break in Exhibit Hall   |   |   |
|   | <table border="0" style="width: 100%;"> <tr> <td style="width: 50%; text-align: center;"><b>Ceramic Micro Systems Track</b></td> <td style="width: 50%; text-align: center;"><b>Ceramic Interconnect Track</b></td> </tr> </table>  | <b>Ceramic Micro Systems Track</b>  | <b>Ceramic Interconnect Track</b>   |
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| Topical Sessions: 10:30 am - 12:10 pm   | <table border="0" style="width: 100%;"> <tr> <td style="width: 50%;"> <b>Session TA1: Materials and Processes for Microsystems</b><br/> <b>Chairs:</b> Dan Krueger, Honeywell; Heiko Thust, Technical University of Ilmenau </td> <td style="width: 50%;"> <b>Session TA2: Co-Firing Processes and Dimensional Control in LTCC</b><br/> <b>Chair:</b> Weiming Zhang, Heraeus Microcircuits </td> </tr> </table>   | <b>Session TA1: Materials and Processes for Microsystems</b><br><b>Chairs:</b> Dan Krueger, Honeywell; Heiko Thust, Technical University of Ilmenau                                     | <b>Session TA2: Co-Firing Processes and Dimensional Control in LTCC</b><br><b>Chair:</b> Weiming Zhang, Heraeus Microcircuits   |
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| 12:10 pm - 1:20 pm  | Lunch in Exhibit Hall   |   |   |
| Topical Session: 1:20 pm - 3:00 pm  | <table border="0" style="width: 100%;"> <tr> <td style="width: 50%;"> <b>Session TP1: Microsystems Applications I</b><br/> <b>Chairs:</b> W. Kinzy Jones, Florida International University; S. (Krish) Krishnamoorthy, CFD Research Corporation </td> <td style="width: 50%;"> <b>Session TP2: Processing and Design of Integrated Passives in LTCC I</b><br/> <b>Chair:</b> Tim Mobley, DuPont </td> </tr> </table>  | <b>Session TP1: Microsystems Applications I</b><br><b>Chairs:</b> W. Kinzy Jones, Florida International University; S. (Krish) Krishnamoorthy, CFD Research Corporation                 | <b>Session TP2: Processing and Design of Integrated Passives in LTCC I</b><br><b>Chair:</b> Tim Mobley, DuPont  |
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| 3:00 pm - 3:30 pm   | Break in Exhibit Hall   |   |   |
| Topical Session: 3:30 pm - 5:30 pm  | <table border="0" style="width: 100%;"> <tr> <td style="width: 50%;"> <b>Session TP3: Novel Synthesis Technology for Multilayer Electronics I</b><br/> <b>Chairs:</b> David Cann, Oregon State University; Jun Akedo, Advanced Manufacturing Research Institute </td> <td style="width: 50%;"> <b>Session TP4: Processing and Design of Integrated Passives in LTCC II</b><br/> <b>Chairs:</b> Torsten Rabe, Federal Institute for Materials Research and Testing; Klaus-Dieter Lang, Fraunhofer IZM </td> </tr> </table> | <b>Session TP3: Novel Synthesis Technology for Multilayer Electronics I</b><br><b>Chairs:</b> David Cann, Oregon State University; Jun Akedo, Advanced Manufacturing Research Institute | <b>Session TP4: Processing and Design of Integrated Passives in LTCC II</b><br><b>Chairs:</b> Torsten Rabe, Federal Institute for Materials Research and Testing; Klaus-Dieter Lang, Fraunhofer IZM |
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| 5:30 pm - 7:00 pm   | Reception in Exhibit Hall   |   |   |
| <b>Wednesday, April 26</b>  |   |   |   |
| 7:00 am - 5:00 pm   | Registration  |   |   |
| 10:00 am - 4:00 pm  | Exhibit Hours   |   |   |
| 8:30 am - 10:00 am  | <b>Session WA1: International Session on Microsystems</b><br><b>Chair:</b> Dean Anderson, Penn State University   |   |   |
| 10:00 am - 10:30 am   | Break in Exhibit Hall   |   |   |
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| 3:00 pm - 5:00 pm   | <b>Session WP3: Interactive Forum (Poster Session)</b><br><i>One-on-One Interactive Forum. This is your chance for detailed interaction with authors whose work is too good to miss.</i><br><b>Chairs:</b> Martin Oppermann, EADS Deutschland GmbH; Walter Rothlingshofer, Robert Bosch   |   |   |
| <b>Thursday, April 27</b>   |   |   |   |
| 7:30 am - Noon  | Registration  |   |   |
| 8:20 am - 9:50 am   | <b>Session THA1: International Session on Microsystems</b><br><b>Chairs:</b> Dave Wilcox, Consultant; Leszek Golonka, Wroclaw University  |   |   |
| 9:50 am - 10:20 am  | Break   |   |   |
| 10:20 am - Noon   | <b>Session THA2: Novel Synthesis Technology for Multilayer Electronics II - Aerosol Deposition</b><br><b>Chair:</b> Yong Cho, Yonsei University   |   |   |
| Noon  | Closing Remarks   |   |   |